/ Revised record

D	2017-5				
E	2021-1-27	4/7	e0.5-0.7 0.5-0.8 5 7		

MB24F~MB220F

Rev.E Jan.-2021

DATA SHEET

/ Descriptions

2.0A MBF

2.0A Surface Mount Schottky Bridge,MBF thin package.

/ Features

40V~200V 2.0A

High Surge Current Capability,Reverse Voltage:40to200V,Forward Current:2.0A,Designed for Surface Mount Application.Halogen free product.

/ Applications

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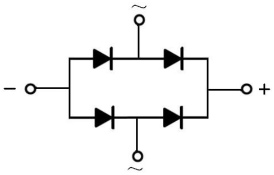
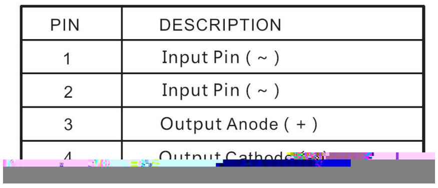
General purpose.

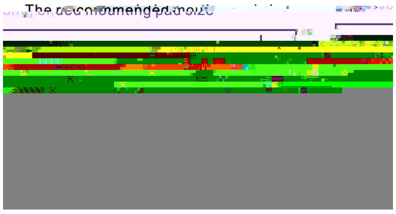
/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode



The recommended mounting pad size

/ Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating					Unit
		MB24F	MB26F	MB28F	MB210F	MB220F	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	40	60	80	100	200	V
Maximum RMS Voltage	V_{RMS}	28	42	56	70	140	V
Maximum DC Blocking Voltage	V_{DC}	40	60	80	100	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	2.0					A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	50		40			A
Typical Junction Capacitance$^{1)}$	C_j	220	80				pF
Typical Thermal Resistance$^{2)}$	$R_{\theta JA}$	75					℃/W
Operating Junction Temperature Range	T_j	-55~+125					℃
Storage Temperature Range	T_{stg}	-55~+150					℃

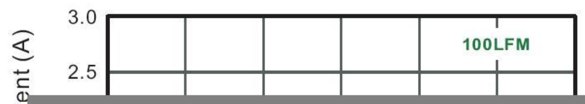
Note:

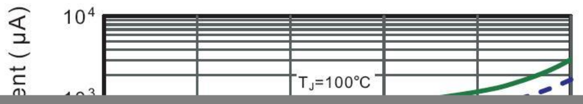
1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×(5×5mm^2）copper pad.

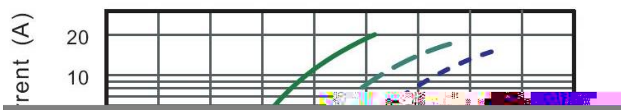
/ Electrical Characteristics(Ta=25)

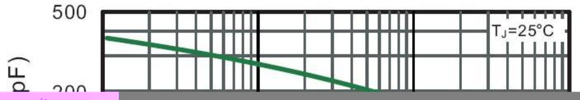
Parameter	Symbol	Test Conditions	数值 Rating					Unit
			MB24F	MB26F	MB28F	MB210F	MB220F	
Max Instantaneous Forward Voltage	V_F	I_F=2.0A	0.55	0.70	0.85			V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25℃	0.5			0.3		mA
		T_a=100℃	10			5.0		mA

/ Electrical Characteristic Curve



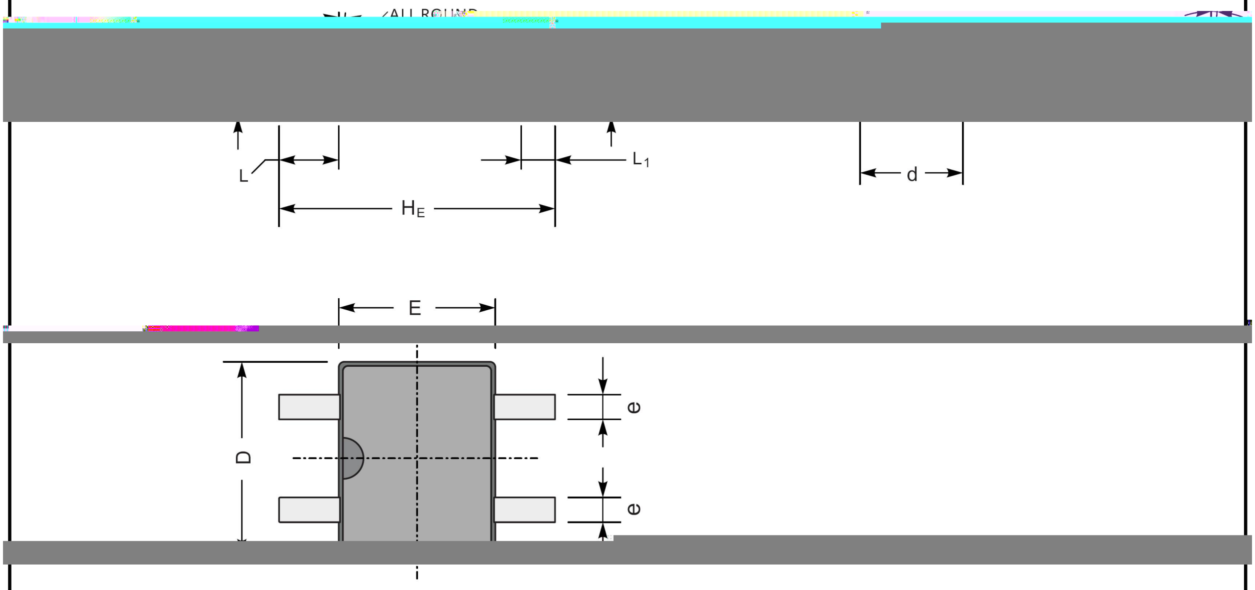






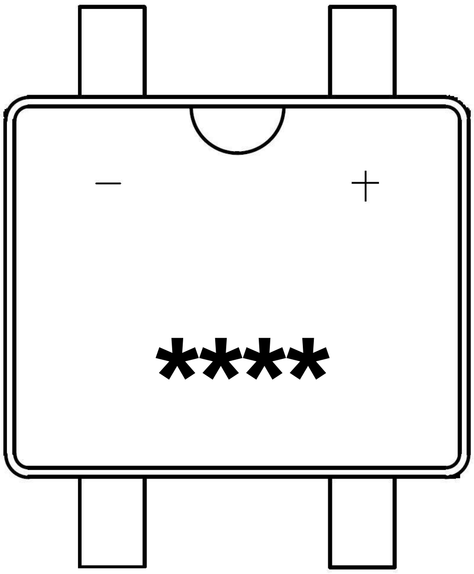
/ Package Dimensions

MBF



UNIT		A	C	D	E	H_E	d	e	L	L_1	a	[illegible]
	min	1.2	0.15	4.5	3.6	6.4	2.3	0.5	1.3	0.5	—	7°

/ Marking Instructions



MB24F

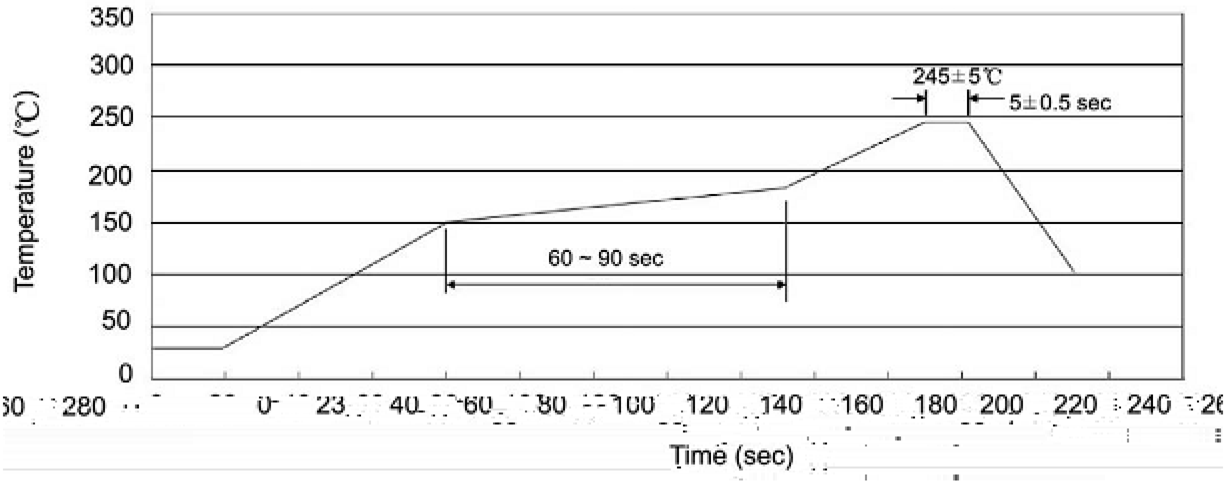
**** 1 * 3 *

Note:

MB24F Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



	Note:
1 25 150 60 90sec;	1.Preheating:25~150℃, Time:60~90sec.
2 245±5 5±0.5sec;	2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3 2 10℃/sec.	3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

260±5℃ 10±1 sec. Temp.:260±5℃ Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱